

# TG-A38KF

## High Performance Thermal Pad

REACH Compliant

RoHS Compliant

UL Compliant

### Features

- Great thermal conductivity
- Difficult to be deformed
- Fiberglass on one side and electrical insulation
- One side inherent tack

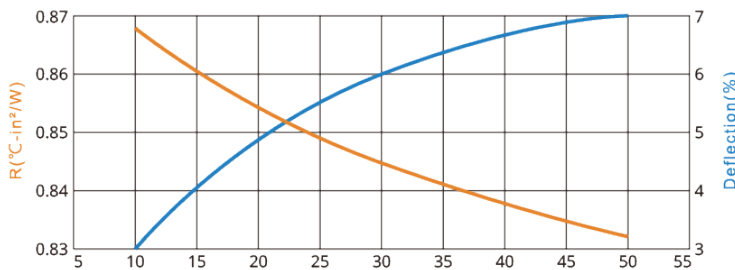
### Applications

Best for low and medium power applications

Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, etc.

### Properties

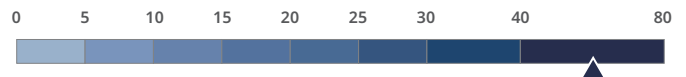
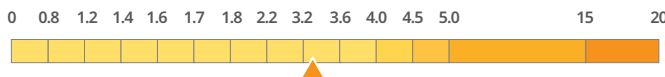
Thermal Resistance vs. Pressure vs. Deflection



Pressure (psi)	R (°C-in²/W)	Deflection (%)
10	0.868	3
30	0.845	6
50	0.832	7

Thermal Conductivity : 3.3 W/mK

Hardness : 60 (Shore 00)



Properties	TG-A38KF	Unit	Tolerance	Test Method
Thermal Conductivity	3.3	W/mK	±10%	ASTM D5470
Thickness	0.5~10.0	mm	-	ASTM D374
	0.0197~0.394	inch	-	ASTM D374
Color	Blue	-	-	Visual
Reinforcement Carrier	Fiberglass mesh	-	-	-
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	>8	KV/mm	±10%	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Density	3.1	g/cm <sup>3</sup>	±10%	ASTM D792
Working Temperature	-40~+200	°C	-	-
Volume Resistance	3 × 10 <sup>12</sup>	Ohm-m	-	ASTM D257
Elongation	110 (Silicone Side)	%	-	ASTM D412
Standard Format	Sheet	-	-	-
Hardness	60 (Silicone Side)	Shore 00	±8	ASTM D2240

Pre-cut for different shapes